



PART NO. : TG111-S212NWRL

50PIN 0.040" LEAD PITCH SMT PACKAGE

DESIGNED FOR DUAL-PORT GIGABIT, IEEE802.3ab OR
FOUR-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS

COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH
350mA CURRENT CARRYING CAPACITY FOR PoE

RoHS COMPLIANT

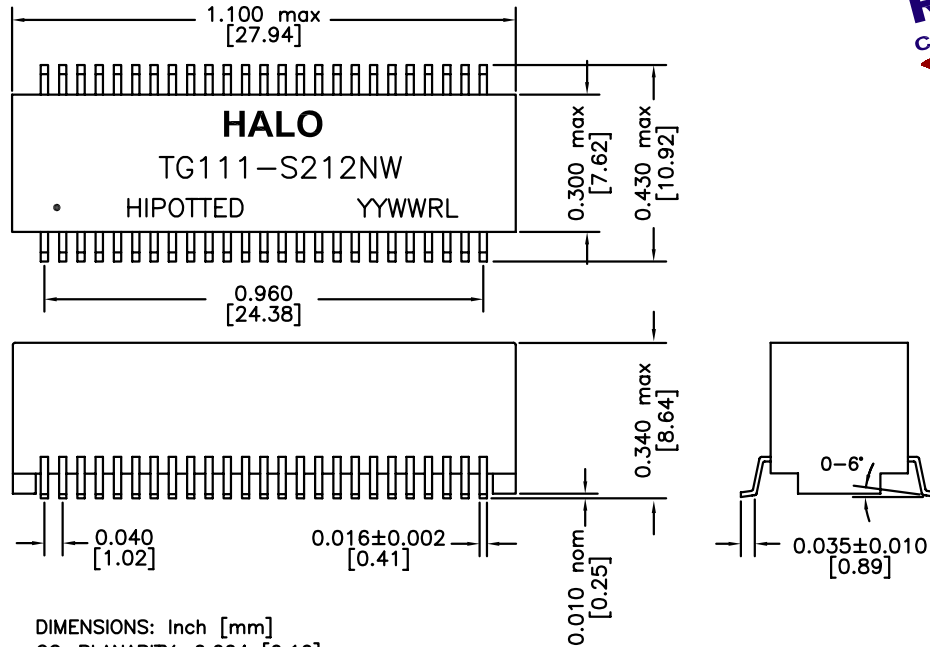
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

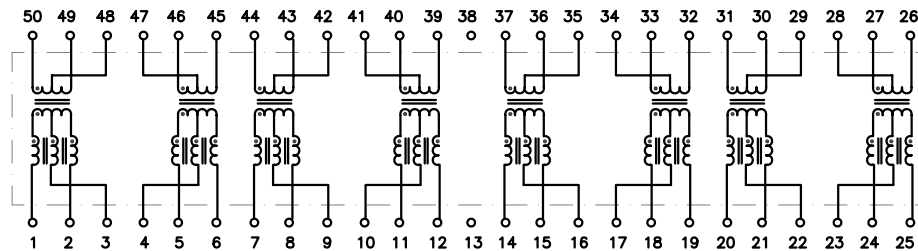
OPERATING TEMPERATURE 0/70°C

ELECTRICAL SPECIFICATIONS @ 25° C

URNS RATIO	1CT:1CT±2%
OCL (100KHz,0.1Vrms,8mADC)	350µH min
INSERTION LOSS 1-100MHz	-1.1dB max
RETURN LOSS 1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CMR 1-100MHz	-40dB typ
CROSSTALK 1-30MHz	-50dB typ
60MHz	-45dB typ
100MHz	-40dB typ
ISOLATION	1,500Vrms



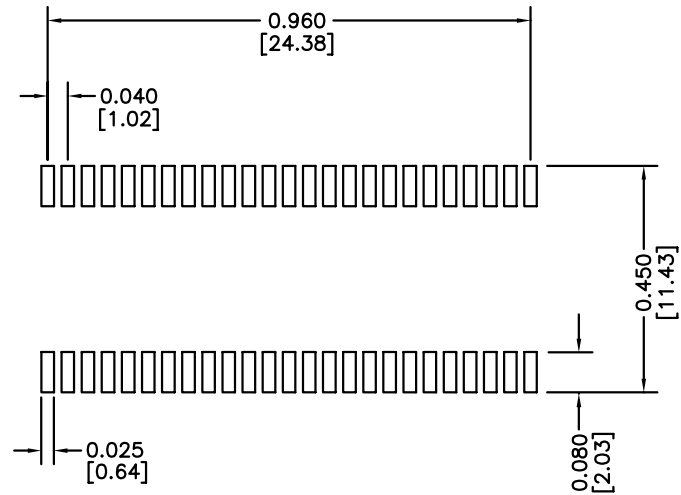
DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST/GIGABIT ETHERNET	DRAWN PETER LU	11/8/05	A	FIRST ISSUE	11/8/05
PART NO.	TG111-S212NWRL	CHECKED LEI KEONG	3/20/08	B	PROD. RELEASE	12/21/06
SCALE	NONE	APPROVED PETER LU	3/20/08	C	REV. TOE LENGTH TOL.	3/20/08
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RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

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SCALE	NONE	PAGE 2 OF 2	FILE S212NWRL.DWG				